

LOR 3A – run sheet

Kayaku Advanced Materials

nanyte.com/photoresists/lor-3a · last updated 2026-07-26

Thickness: 0.3–0.6 μm

Softbake: 180 °C · 3 min · hotplate

Develop: Developer 0.26N (2.38%) TMAH metal-ion-free developer – e.g. Shipley/Rohm and Haas CD-26 or TOK NMD-3 – is the developer class the LOR-A series (including LOR 3A) is optimized for; the LOR-B series is instead optimized for lower-normality/metal-ion-bearing developers such as AZ 400K 1:4 or Shipley MF-319. · Dilution ready-to-use (as supplied) · Rinse DI water · Method immersion (spray development is recommended instead for thick, >2 μm LOR/PMGI stacks, for straighter sidewalls)